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1.0 INTRODUCTION

1.1<u>SCOPE</u>

This document describes the functional and test requirements for the PCI Express[™] card-edge connector. The connector is designed to meet the requirements of the PCI Express Card Electromechanical Specification and certain customer specifications not covered by the PCI-SIG document.

1.2<u>APPLICABLE DOCUMENTS</u>

- 1.2.1 Solderability : BUS-19-002/A
- 1.2.2 PCI Express Card Electromechanical Specification
- 1.2.3 EIA -90, EIA-364-
 - 09,17,20,21,28,31,32,65,70,101,108,638
- 1.2.4 PCI Express Connector High Speed Electrical Test Procedure.
- 1.2.5 FCI drawing, PCI Express connector, inspection & customer copy.
- 1.2.6 FCI drawing, solder washer, 78523 : inspection copy.

1.3 DRAWING PRECEDENCE

In the event of conflict between this document and product prints, the product prints shall take precedence.

2.0 GENERAL REQUIREMENTS

- 2.1 The connector has the following characteristics: 1.00m(0.040") pitch, X1, X4, X8, X16 sizes, through hole or straddle mount configuration, rectangular outline, plastic peg or two forklock holdowns requiring TH holes on PCB.
- 2.2 Visual examination, unless otherwise specified, shall be made at 7X.
- 2.3 Silicone compounds (mold releases, lubricants, etc.) May not be used in the manufacturing processes.
- 2.4 Flammability to be rated UL 94V-0.
- 2.5 Unless otherwise specified, tests that require the use of a pc edge card shall use the following
 - 2.5.1Card material: FR-4 glass epoxy.
 - 2.5.2Thickness: 1.57 +/- 0.13 (0.062 +/- 0.005 inch)
 - 2.5.3Trace material: 0.035 (0.0014 inches), copper.
 - 2.5.4Trace plating: 0.76 micrometers (30 microinches) minimum gold over 1.27 micrometers (50 microinches) minimum unbrushed nickel

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2.5.5Pad and trace design: pad and trace design shall follow PCI Express standard as depicted in customer drawing.

2.6 SOLDERTAIL TERMINATION

Tests requiring termination of the soldertails to a PC board shall be prepared as follows:

- 2.6.1A 2.4mm +/- 0.13 (0.094 +/- 0.005) thick FR-4 glass epoxy board having no internal ground planes with plated thru holes in the pattern specified in AFCI customer drawing, shall be used.
- 2.6.2 Solder washers, AFCI part number 78523-001, shall be applied to the tails, and the connector vapor phase reflowed at 215°C (419°F) for a time not to exceed 2 minutes.

3.0 MECHANICAL REQUIREMENTS

3.1 EXAMINATION OF PRODUCT

Samples must comply to applicable FCI product prints.

3.2 INSERTION / WITHDRAWAL FORCE- ADD IN CARD PER EIA-364-13 Mating cycle is with maximum/minimum thick

Mating cycle is with maximum/minimum thickness gage at a rate of 25.4 mm/minute.

- 3.2.1 Maximum insertion force is 1.15 N max. per contact pair when measured with a 1.70 +0.00/-0.01(0.067 +0.000/ -0.004 inches) thick hardened steel card made to the dimensions shown for the PCI Express expansion board in the FCI customer drawing. The card has a R0.05 min., R0.10 max.(sharpedge)and the surface roughness in connector area to be 0.10 micrometers (4 microinches) maximum.
- 3.2.2 Withdrawal force is 0.15N minimum per contact pair when measured with a 1.44 +0.01/-0.00 (0.067 +0.004/-0.000 inches) thick hardened steel card made to the dimensions shown for the PCI Express expansion board in the FCI customer drawing. The card has a R0.05 min., R0.10 max (sharp edge) and the surface roughness in the connector area to be 0.10 micrometers (4 microinches) maximum.
- 3.3 CONTACT RETENTION

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Minimum retention force of terminals in the connector housing to be 5N each. Pull rate to be 1.27 mm/min.

3.4 BOARD RETENTION / INSERTION FORCES

- 3.4.1 Board retention / insertion forces should be checked on an 1.57 +/- 0.13 (0.062 +/- 0.005 inch) thick segment of FR-4 glass / epoxy circuit board segment with a hole of diameter as described below drilled through. Connectors should have all contacts present. Forces apply to connectors with plastic pegs and metal board locks.
- 3.4.2 Maximum insertion force(including all types post or straddle mount solder tails) to seat connector in PCB(including straddle mount or through PCB)are:

36	pos	2.14	kg	max.
64	pos	3.91	kg	max.
98	pos	7.45	kg	max.
164	pos	7.45	kg	max.

3.5 SOLDERABILITY

Per J-STD-002

- a. steam age for 1 hour
- b. contact areas evaluated shall meet 95% minimum coverage.

4.0 ELECTRICAL REQUIREMENTS

Unless otherwise specified, all measurements should be performed in the following ambients:

relative humidity:	50%	or	less				
temperature:	25°C	+/-	5°c				
barometric pressure:	711	to 8	12 mm	mercury	(at	sea	level)

4.1 LOW LEVEL CONTACT RESISTANCE EIA-364-23

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- 4.1.1Solder connector to pc board per section 2.6 and insert card per section 2.5
- 4.1.2Resistance measurements should be made from the underside of the pc board to the PTH in the add-in card above the contact pad. The test current shall be 100 milliampere d.c. max. with a maximum open circuit voltage of 20 millivolts D.C. See figure 1.0 for attachment of current and voltage leads.
- 4.1.3Requirement is 30 milliohms maximum initial, with change of 10 milliohms maximum after exposure testing.

CONTACT RESISTANCE TEST SET UP THROUGH HOLE FIGURE 1



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4.2 INSULATION RESISTANCE

Requirement is 1000 megohm minimum at 100 + / - 10% vdc when tested to EIA-364-21 per spec. The connector shall not be mated during insulation resistance measurement.

4.3 DIELECTRIC WITHSTANDING

Per EIA-364-20 method B per spec. Test potential to be 300 VAC RMS, 60 HZ, and applied for 1 minute. No breakdown should occur. Test is performed with connector unmated.

4.4 CONTACT CURRENT RATING

1.1 amp per contact minimum per EIA-364-70, method 2 and PCI Express Connector High Speed Electrical Test Procedure. The temperature rise shall not exceed 30 degree C. Ambient condition is still air at 25°C.

4.5 INSERTION LOSS

Per EIA-364-101 and PCI Express Connector High Speed Electrical Test Procedure. Requirements: Less than or equal to 1dB up to 1.25 GHz

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Less than or equal to $1.6 \times (F-1.25)+1$) db between 1.25GHz and 3.75GHz. Less than or equal to 5 dB at 3.75 GHz

4.6 RETURN LOSS

Per EIA-364-108 and PCI Express Connector High Speed Electrical Test Procedure. Requirements: Less than or equal to -12dB up to 1.3 GHz Less than or equal to -7dB up to 2.0 GHz Less than or equal to -4dB up to 3.75 GHz

4.7 CROSSTALK: NEXT

Per EIA-90 and PCI Express Connector High Speed Electrical Test Procedure. Requirements: Less than or equal to -32 dB max up to 1.25 GHz Less than or equal to $-(32 - 2.4 \times (F-1.25))$ db between 1.25 GHz and 3.75GHz. Less than or equal to -26 dB max up to 3.75 GHz

5.0 ENVIRONMENTAL REQUIREMENTS (Per EIA-364-1000.01)

5.1 THERMAL SHOCK

Per EIA-364-32, test condition I, 10 cycles

5.2 CYCLIC TEMPERATURE AND HUMIDITY

Per EIA-364-31, 24 cycles

5.3 TEMPERATURE LIFE (Pre-conditioning)

Per EIA-364-17, method A, 92 hours at 105°C

5.4 TEMPERATURE LIFE

Per EIA-364-17, method A, 168 hours at 105°C

5.5 VIBRATION

Per EIA-364-28, test condition VII, test condition letter D. Requirements: no evidence of physical damage

5.6 DURABILITY (Pre-conditioning) CYCLE RATE : 500 MATING / HOUR Per EIA-364-09, 20 cycles

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5.7 DURABILITY CYCLE RATE : 500 MATING / HOUR Per EIA-364-09, 50 cycles

5.8 MIXED FLOWING GAS

Per EIA-364-65, class IIA, 10 days exposure. Expose connectors unmated for 2/3 of the total duration. Mate each connector to the same add-in card that it was mated to in temperature life (preconditioning) and expose for the remainder of the test duration.

5.9 RESEATING

Manually plug/unplug the card and connector, 3 cycles.

5.10RESISTANCE TO SOLDERING HEAT

Per EIA-364-56 procedure 3, test condition C. $260^{\circ}\pm5^{\circ}C$ $10^{\pm}2$ seconds

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6.0 Test Matrix for 1X,4X,8X,& 16X

	TABLE 1 - QUALIFICATION TESTING MATRIX									
		TEST GROUP	TEST GROUP	TEST GROUP	TEST GROUP	TEST GROUP	TEST GROUP	TEST GROUP	TEST GROUP	TEST GROUP
		1	2	3	4	5	6	7	8	9
			•			TEST		•	•	
TEST	PARA		1	1	1	SEQUENCE			1	1
Examination of Product	3.1	1	1	1	1	1	1	1	1	1
Insertion/Withdrawal Force - Add In Card	3.2					3				
Contact Retention	3.3					5				
Board Retention /Insertion Forces	3.4					2				
Solderability	3.5					4				
Low Level Contact Resistance	4.1	2,5,7	2,5,8, 10	2,5,7	2,5,7,9 ,11			3,5		
Insulation Resistance	4.2		7							
DWV	4.3							2,6		
Contact Current Rating	4.4								2	
Insertion Loss	4.5						2			
Return Loss	4.6						3			
Crosstalk	4.7						4			
Thermal Shock	5.1		4		8					
Cyclic Temp and Humidity	5.2		6							
Temperature Life (pre- conditioning)	5.3			4	4					
Temperature Life	5.4	4								
Vibration	5.5			6						
Durability (pre- conditioning)	5.6	3	3	3	3					
Durability	5.7							4		
Mixed Flowing Gas	5.8				6					
Reseating	5.9	6	9		10					
Resistance to soldering heat	5.10									2
Sample Quantity / Group		16X-5 ⁽¹⁾ 200-5 ⁽¹⁾ 280-5 ⁽¹⁾	16X-5	16X-5 200-5 280-5	16X-10 ⁽²⁾	16X- 10,8X-10, 4X-10,1X- 10 ⁽³⁾ 200-10, 280-10	4x-3	16X-10 ⁽⁴⁾ 200-10 ⁽¹⁾ 280-10 ⁽¹⁾		16X-3 Plasti c peg 16X-3 board lock

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Notes:

- samples for test groups 1,2,3,6 & 8 have metal hold downs, phos bronze contacts and 0.38 micrometers (15 u") gold plate, and black housings.
 samples for test group 4:
 - a. 5 each same as note 1
 - b. 5 each same as note except with 0.76 micrometers (30u") gold plate.
- 3. samples for test group 5:
 a. 5 each same as note 1
 b. 5 each same as note except with plastic locating pegs.
 4. samples for test group 7:
 a. 5 each same as note 1
 b. 5 each same as note except with 0.76 micrometers (30U") gold plate.
- 5. samples for test group 8:
 - a. 2 each same as note 1
 - b. 2 each same as note except with 0.76 micrometers (30U") gold plate.

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REVISION RECORD

REV	PAGE	DESCRIPTION	ECR #	DATE
A	ALL	RELEASED	T03-0302	07/21/2003
В	ALL	Add 5.10 on Sheet 7 Add group 9 on sheet 8	т03-0463	10/17/03
С	ALL	Modify 5.8 on sheet 7	T03-0513	
D	ALL	3.2 add PER EIA-364-13 & cycle rate 4.1 add PER EIA-364-23 5.6 & 5.7 add cycle rate	T04-0114	03/10/04
Е	ALL	ADD STRADDLE MOUNT TYPE	Т04-0341	08/04/04
F	ALL	ADD 3.4.3	T04-0414	11/23/04
G	ALL	MODIFY 3.4.2, REMOVE 3.4.3 AND CHANGE FORM	Т06-0120	06/20/06
Н	4	SOLDERABILITY-REFERENCE DOCUMENT WAS REPLACED BY "J- STD-002"	T08-1128	07/04/08

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